



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): YOSHIHARA et al.

Atty. Dkt.: 15-015

Serial No.: 09/977,681

Group Art Unit: 2815

Filed: October 16, 2001

Examiner: BAUMEISTER BRADLEY

Title: SEMICONDUCTOR SENSOR CHIP  
HAVING DIAPHRAGM AND  
METHOD OF MANUFACTURING  
THE SAME

Assistant Commissioner for Patents  
Washington, D.C. 20231

Date: Nov. 27, 2002

#8/A  
Amended  
J. Miller  
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Typed Name: DAVID G. POSZ

Signature: 

AMENDMENT

Sir:

In response to the office action dated September 5, 2002, please enter the following amendments and consider the appended remarks.

IN THE CLAIMS

Please cancel claims 1 - 5 and 9 without prejudice.

Please amend claim 6 as follows:

6. (Amended) A semiconductor sensor chip comprising:

a semiconductor substrate having a front portion and a rear portion, the front portion and the rear portion having a different conductivity to form a P-N junction plane parallel to front and rear surfaces of the semiconductor substrate;

sub B1  
A1